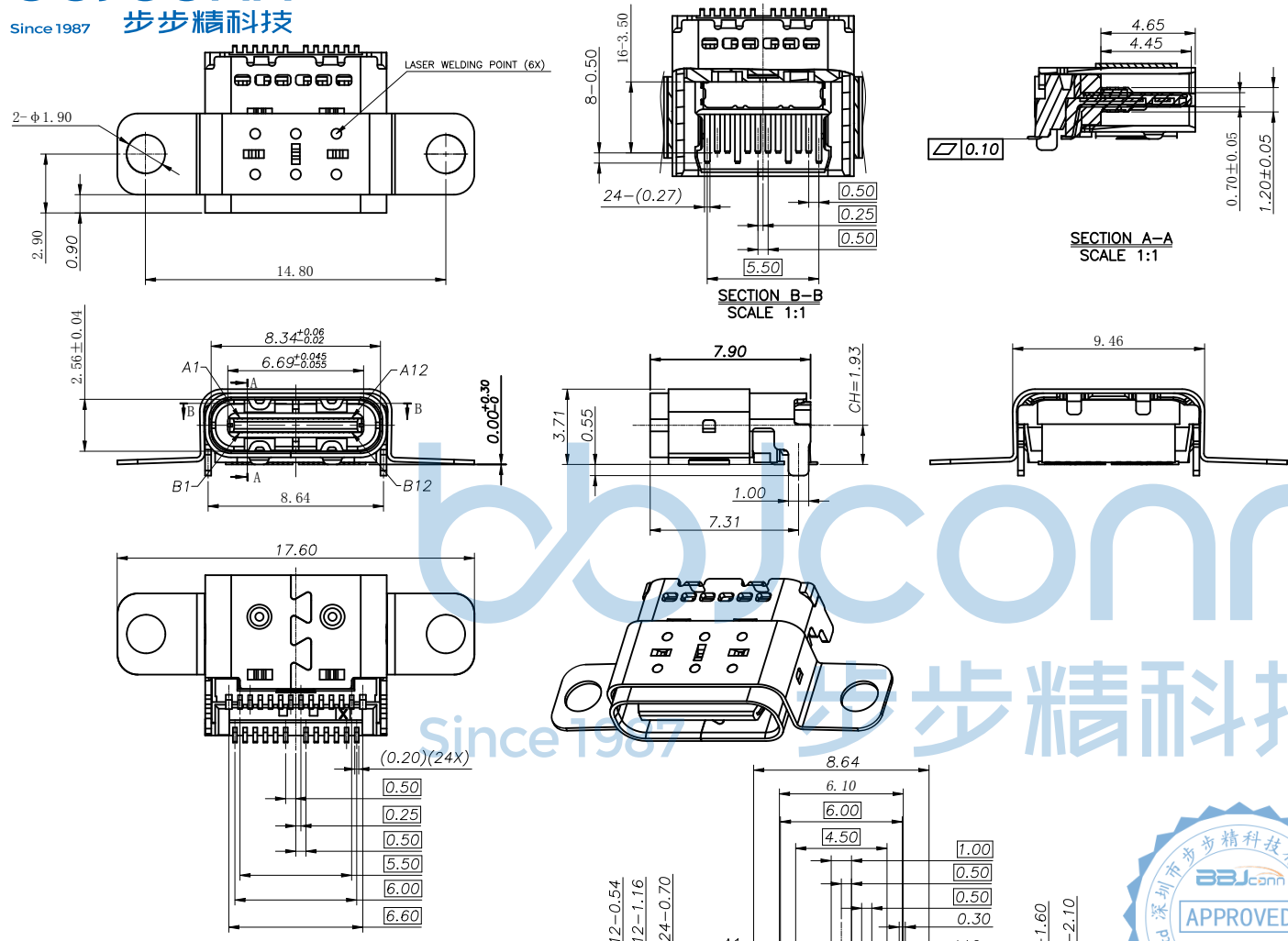


REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP

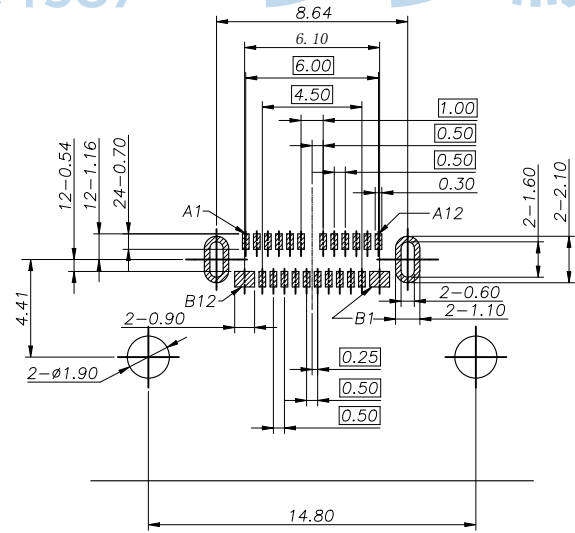


- NOTE:
- MATERIAL SPECIFICATION:
    - HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC, UL94 V-0.
    - CONTACTS: COPPER ALLOY
    - MID PLATE: STAINLESS STEEL
    - FRONT SHELL: STAINLESS STEEL
    - EMI PLATE: STAINLESS STEEL
    - TOP SHELL: STAINLESS STEEL
  - PLATING SPECIFICATION:
    - CONTACTS:
      - Ni 50u" MIN. UNDER PLATED OVER ALL.
      - Au PLATED ON THE FUNCTIONAL AREA OF CONTACT. (GOLD PLATING THICKNESS FOLLOW)
      - PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW
    - FRONT SHELL & TOP SHELL:
      - Ni 30u" MIN. UNDER PLATED OVER ALL.
    - EMI PLATE:
      - CLEAR ONLY
    - MIDDLE PLATE:
      - Ni 40u" MIN. UNDER PLATED OVER ALL.
  - MECHANICAL PERFORMANCE,
    - TIN 80u" MIN. PLATED ON SOLDER AREA.
    - 3-1. INSERTION FORCE: 0.5~2.0kgf.
    - 3-2. REMOVAL FORCE: 0.8kgf~2.0kgf.
    - 3-3. DURABILITY: 10000 CYCLES.
  - ELECTRICAL PERFORMANCE,
    - CURRENT RATING: 5.0A  
VOLTAGE RATING: 5.0V
    - LLCR:
      - VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
      - SHIELD: 50mΩ/ MAX.
      - LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
    - INSULATION RESISTANCE: 100MΩ MIN
    - DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE.
  - ENVIRONMENTAL PERFORMANCE:
    - OPERATING TEMPERATURE: -25° C~+85° C.
    - THE PEAK TEMPERATURE ON THE BOARD SHALL
  - IR REFLOW:
    - BE MAINTAINED FOR 10 SECONDS AT 260° C.
  - COPLANARITY OF SMT PINS SOLDER TAIL IS 0.10 MAX. BEFORE REFLOW AND AFTER REFLOW



USB TYPE-C PIN ASSIGNMENTS

PIN NUMBER	SIGNAL NAME	PIN NUMBER	SIGNAL NAME
A1	GND	B12	GND
A2	TX1+	B11	RX1+
A3	TX1-	B10	RX1-
A4	Vbus	B9	Vbus
A5	CC1	B8	SBU2
A6	Dp1	B7	Dn2
A7	Dn1	B6	Dp2
A8	SBU1	B5	CC2
A9	Vbus	B4	Vbus
A10	RX2-	B3	TX2-
A11	RX2+	B2	TX2+
A12	GND	B1	GND



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PDWG. NO: 0470-1

DR. TSP

APPD. JM\_Zheng

CHKD. LYX

NAME: TYPE-C 24P 母座 双壳 锁螺丝式 缺P 第三代MD 两脚插+两脚贴片 双排SMT L=7.90 CH=1.93 编带

PJ. NO.:

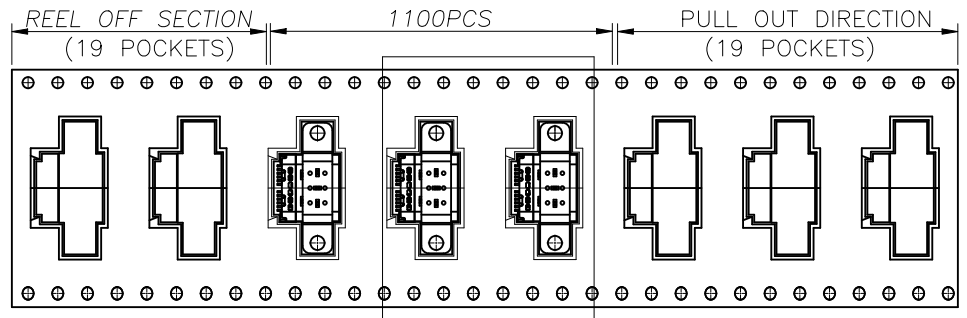
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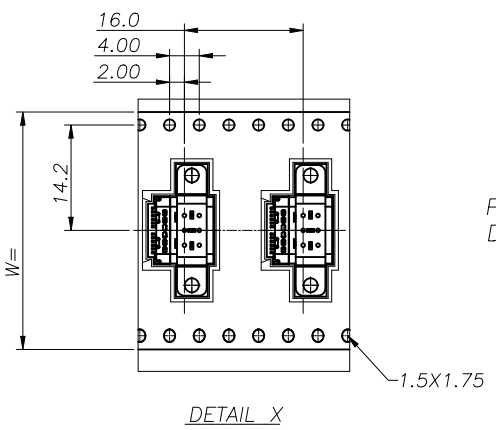
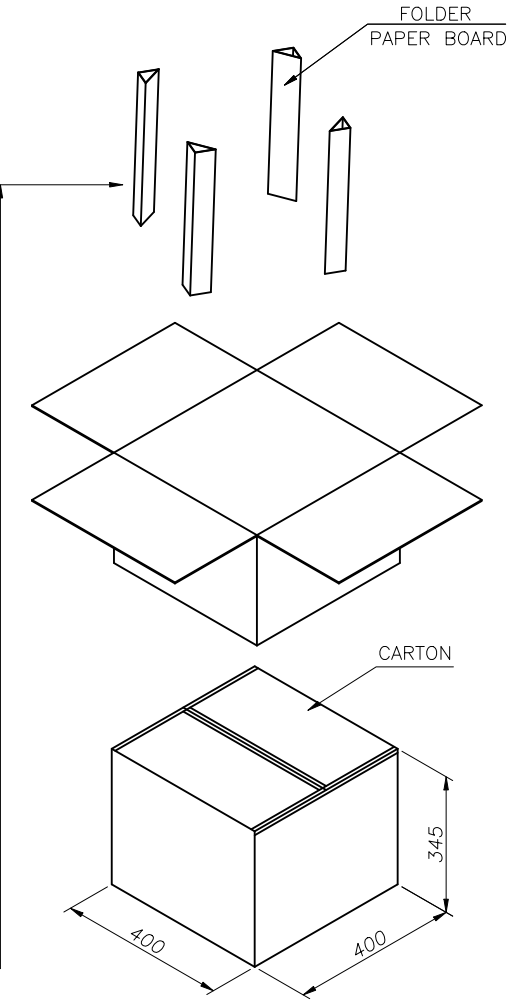
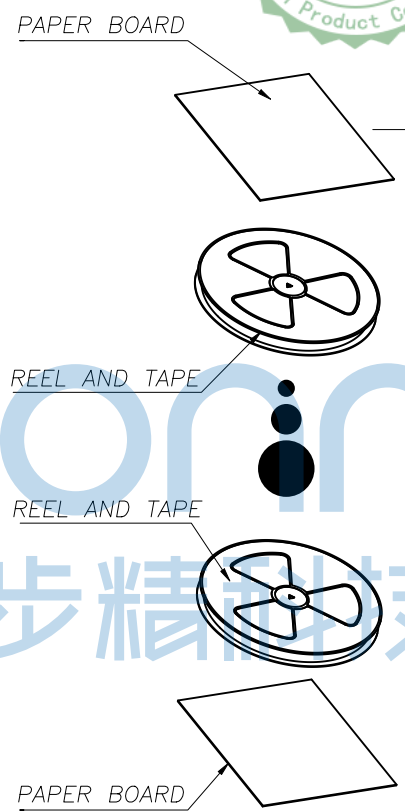
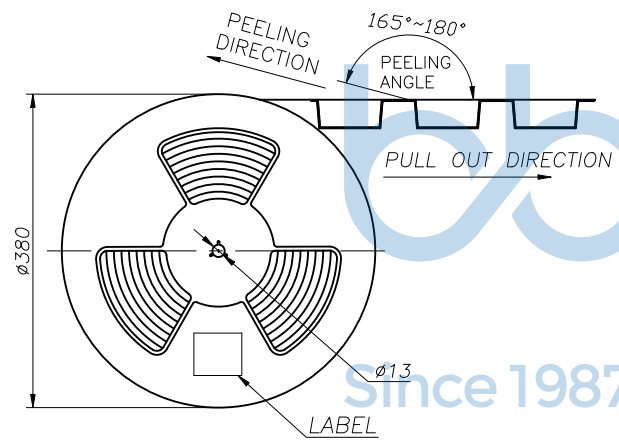
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REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP



SEE DETAIL X



	REEL/TRAY	CARTON
CONNECTOR (PCS)	1100	8800

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深圳市步步精科技有限公司  
工程部部长

NAME: TYPE-C 24P 母座 双壳 锁螺丝式 缺P 第三代MD 两脚插+两脚贴片 双排SMT L=7.90 CH=1.93 编带

PJ. NO.:  
SIZE: A4 | DRW NO.:

FINISH: SEE NOTES | MAT'L.: SEE NOTES  
SCALE: N/A | REV.: A0 | UNIT: mm | PAGE: 2/2